

# Benvenuto in O-Leading

Siamo produttori di PCB professionali con oltre dieci anni di esperienza. Gamma di prodotti: PCB singolo, doppio lato, multistrato, PCB flessibile e MCPCB. Siamo in grado di fornire un servizio prototipo rapido: S / S in 24 ore, 4-8 giocatori in 48-96 ore lavorative di produzione.

[\(Produttore di schede multistrato Cina\)](#)

PIATTI DI RAME MINIMO MINIMO .025 AVG, .020 MIN. I FORI NON POSSONO ESSERE COLLEGATI

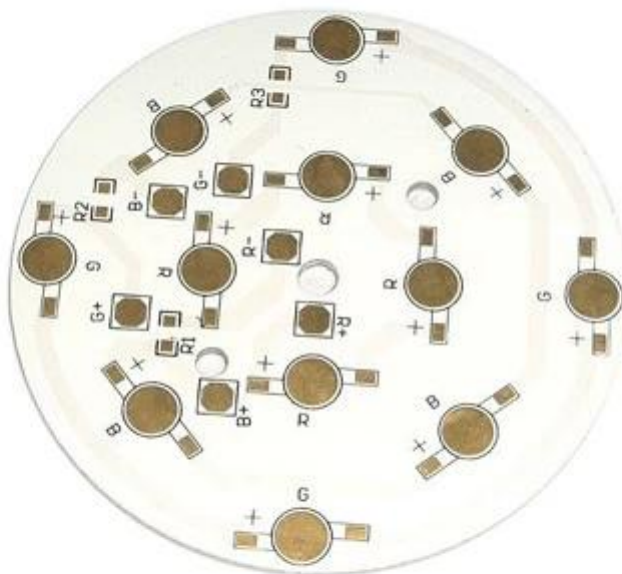
Confezione con pellicola a bolle trasparente incolore, 25 pezzi / borsa, mettere l'essiccante nel fianco, mettere la scheda dell'indicatore di umidità sul lato superiore

CLICCA QUI PER MAGGIORI INFORMAZIONI : [Commerci all'ingrosso di ceramica Flash Gold](#)

## Descrizione del prodotto

P / N PCB	LC057-V1
Conteggio dei livelli	1L
Materiale	Ceramica di base
Board thk	1,6 millimetri
thk di rame	11 once
Dimensione del foro più piccola	/
Numero di fori (pezzi)	/
linea w / s	15mil
Controllo di impedenza. S / N (% Tol)	N
Finitura superficiale	ENIG (Au: 0.05um)
Maschera per saldatura Serigrafia	Bianco / N / A
Dimensioni scheda singola	Dim X (mm): 89; Dim Y (mm): 175
Panelisation	Dim X (mm): 89; Dim Y (mm): 175; No di UPS: 1
Speciale	N
Routing / Punzonatura	CNC

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[www.o-leading.com](http://www.o-leading.com)

[Produttore di layout PCB Cina](#)

## FAQ

1. In che modo O-Leading garantisce la qualità?

Il nostro elevato standard di qualità è raggiunto con quanto segue.

1. Il processo è rigorosamente controllato secondo gli standard ISO 9001: 2008.
2. Ampio utilizzo di software nella gestione del processo di produzione
3. Attrezzature e strumenti di collaudo all'avanguardia. Per esempio. Sonda volante, ispezione a raggi X, AOI (Automated Optical Inspector) e ICT (test in-circuit).
4. Dedicato team di controllo qualità con processo di analisi dei casi di fallimento
5. Formazione e formazione continua del personale

2. In che modo O-Leading mantiene il tuo prezzo competitivo?

Nell'ultimo decennio, i prezzi di molte materie prime (ad es. Rame, prodotti chimici) sono raddoppiati, triplicati o quadruplicati; La valuta cinese RMB si è apprezzata del 31% rispetto al dollaro USA; E anche il nostro costo del lavoro è aumentato in modo significativo. Tuttavia, O-Leading ha mantenuto costanti i nostri prezzi. Questo appartiene interamente alle nostre innovazioni nel ridurre i costi, evitare gli sprechi e migliorare l'efficienza. I nostri prezzi sono molto competitivi nel settore allo stesso livello di qualità.

Crediamo in una partnership vantaggiosa per tutti con i nostri clienti. La nostra partnership sarà

reciprocamente vantaggiosa se possiamo offrirti un vantaggio in termini di costi e qualità.

3. Quali tipi di schede possono elaborare O-Leading?

Schede comuni FR4, high TG e senza alogeni, Rogers, Arlon, Telfon, schede a base di alluminio / rame, PI, ecc.

4. Quali dati sono necessari per la produzione di PCB?

È meglio fornire i dati nel formato Gerber 274-X. Inoltre, è possibile elaborare anche Cam350, CAD, Protel 99se, PADS, DXP ed Eagle.

5. Qual è il flusso di processo tipico per PCB multistrato?

Taglio del materiale → Pellicola a secco interna → attacco interno → AOI interno → Multi-bond → Strato impilato verso l'alto Premendo → Foratura → PTH → Placcatura pannello → Pellicola asciutta esterna → Placcatura a motivo → Incisione esterna → AOI esterno → Maschera di saldatura → Contrassegno componente → Finitura superficiale → Instradamento → E / T → Controllo visivo.

## La nostra squadra



Factory PCB



Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

Factory SMT





# certificazioni

CICC INSPECTION CERTIFICATION



**嘉泰认证**

**QUALITY MANAGEMENT SYSTEM CERTIFICATE**  
Certificate No: 18118Q10347R05

**We hereby certify that**  
**O-LEADING SUPPLY CHAIN(HK) CO.,LIMITED**  
Credit No: 61691591-000-07-18-7  
Registration Add: FLAT/RM 1205 12/F TAI SANG BANK BUILDING 130-132 DES VOEUS ROAD CENTRAL HK  
Business Add: 1213, Floor 13, Fortune Building, Danshui Town, Huiyang District, Huizhou, Guangdong, China

Has implemented and maintains a **Quality Management System** Which fulfills the requirements of the following standards  
GB/T19001-2016 idt ISO9001:2015

**Scope of certification**  
Sales of printed circuit boards

Initial issuance period: February 27, 2018  
Renewal date: April 22, 2019  
This certificate is valid during: April 22, 2019 – February 26, 2021  
This certificate is invalid without CICC qualified label in the following period

First supervision and audit	Second supervision and audit	Qualified mark
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The certification registration number does not include those production stages which fail to be covered by the relevant effective administrative procedures and qualification procedures stipulated by the client. The effectiveness of this certificate shall be restricted to those activities which are covered by the certification. The actual information of this certification can be searched on the internet of CICC www.cicc.com.cn by the site of internet www.cicc.com.cn.






CICC INSPECTION CERTIFICATION



**嘉泰认证**

**质量管理体系认证证书**  
证书号: 18118Q10347R05

**兹证明**  
**诚领供应链(香港)有限公司**  
统一社会信用代码: 61691591-000-07-18-7  
注册地址: 香港中環德輔道中130-132號大生銀行大廈1205室  
经营地址: 广东惠州惠阳淡水南亨西路财富大厦13楼1313

**建立的质量管理体系符合**  
GB/T19001-2016 idt ISO9001:2015 质量标准适用条款的要求

**认证范围**  
印刷线路板的销售

初次获证日期: 2018年02月27日  
换证日期: 2019年04月22日  
证书有效期: 自2019年04月22日至2021年02月26日  
在下列期限内, 未经CICC黏贴合格标贴, 本证书无效

第一次监督	第二次重审	黏贴处
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Test Report

No. SZXEC1900530401 Date: 30 Mar 2019 Page 1 of 6

O-LEADING SUPPLY CHAIN (HK) CO., LIMITED

1313.FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG, CHINA

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. : RP19-005089 - SZ
Date of Sample Received : 22 Mar 2019
Testing Period : 22 Mar 2019 - 30 Mar 2019
Test Requested : Selected test(s) as requested by client.
Test Method : Please refer to next page(s).
Test Results : Please refer to next page(s).

Conclusion : Based on the performed tests on submitted sample(s), the results of Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBDEs) and Phthalates such as Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP), and Diisobutyl phthalate (DIBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

Signed for and on behalf of
SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

Tina Fan
Approved Signatory



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Test Report

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Test Results :

Test Part Description :

Table with 3 columns: Specimen No., SGS Sample ID, Description. Row 1: SN1, SZX19-005304.001, Green"PCB"

Remarks :

- (1) 1 mg/kg = 1 ppm = 0.0001%
(2) MDL = Method Detection Limit
(3) ND = Not Detected (< MDL)
(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC 62321-5:2013, IEC 62321-7-2:2017, IEC 62321-6:2015 and IEC 62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Table with 5 columns: Test Item(s), Limit, Unit, MDL, 0/1. Lists various substances like Cadmium, Lead, Mercury, Hexavalent Chromium, Sum of PBBs, Monobromobiphenyl, Dibromobiphenyl, Tribromobiphenyl, Tetrabromobiphenyl, Pentabromobiphenyl, Hexabromobiphenyl, Heptabromobiphenyl, Octabromobiphenyl, Nonabromobiphenyl, Decabromobiphenyl, Sum of PBDEs, Monobromodiphenyl ether, Dibromodiphenyl ether, Tribromodiphenyl ether, Tetrabromodiphenyl ether, Pentabromodiphenyl ether.



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# ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

## Wiring, Printed - Component

See General Information for Wiring, Printed - Component

**O-LEADING SUPPLY CHAIN (HK) CO LTD**  
 ROOM 1205, 12/F  
 TAI SANG BANK BLDG  
 130-132 DES VOEUS ROAD  
 CENTRAL, HONG KONG

E490354

Type	Cond Width			SS/ DS/ DSO	Max	Max			Meets UL796	C T	
	Min	Cond	Area		Solder	Flame	Class				
	Min	Edge			Thk			Oper			
mm(in)	mm(in)	mic(mil)	Diam	Limits	Temp	DSR	I				
<b>Multilayer (mass laminate) printed wiring boards.</b>											
<b>O-LEADING-401</b>	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-	-
<b>O-LEADING-407</b>	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
<b>Multilayer printed wiring boards.</b>											
<b>O-LEADING-408</b>	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All	*
<b>Single layer printed wiring boards.</b>											
<b>O-LEADING-002</b>	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
<b>O-LEADING-003</b>	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	▲	-
<b>O-LEADING-033</b>	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-
<b>O-LEADING-205</b>	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	-
<b>O-LEADING-206</b>	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	-
<b>O-LEADING-D01</b>	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All	*
<b>O-LEADING-S01</b>	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All	*

WIRING, PRINTED - COMPONENT | UL Product iQ

<b>O-LEADING-S02</b>	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	HB	▲	*
<b>O-LEADING-S03</b>	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All	*

\* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

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## Shipping service





Quick Turn Lead Time		
Layer Count:	Lead Tim	Special Requirement
1L/2L	2-3days	24 Hours,48 Hours
4L	3-4days	48 Hours
6L	4-5days	72 Hours
8L	5-6days	NA
10L	6-7days	NA
12L	7-8days	NA
14L	8-9days	NA

Standard Lead Time		
Layer Count:	Sample Lead Time	Volume order lead time
2L	4 days	10 days
4L	5 days	11 days
6L	6 days	12 days
8L	8 days	14 days
10L	10 days	16 days
12L	12 days	18 days
14L	14 days	20 days
16-32L	18 days	24 days

## Capacità di processo

### Funzionalità di produzione di PCB

Conteggio strati: 1 strato-32 strati

Spessore rame finito □ 1 / 3oz-12oz

Larghezza min linea / spaziatura interna □ 3.0mil / 3.0mil

Larghezza min linea / spaziatura esterna: 4.0mil / 4.0mil

Rapporto di aspetto massimo: 10: 1

Spessore della scheda □ 0,2 mm-5,0 mm

Dimensione massima del pannello (pollici): 635 \* 1500mm

Dimensione minima del foro: 4mil

Tolleranza del foro Plated: +/- 3mil

Blind / Buried Vias (tipi All): Sì

Via Fill (conduttivo, non conduttivo): Sì

Materiale base: FR-4, FR-4hg Tg. Materiale privo di alogeni, Rogers, Base in alluminio,poliimmide,  
Rame pesante

Finiture superficiali: HASL, OSP, ENIG, HAL-LF, argento mmmm,Immersion Tin, dita d'oro, inchiostro al carbonio

## **Capacità di produzione SMT**

Materiale PCB: FR-4, CEM-1, CEM-3, scheda a base di alluminio

Dimensione massima PCB: 510x460mm

Dimensioni min PCB: x 50x50mm

Spessore PCB □ 0,5 mm-4,5 mm

Spessore della scheda □ 0,5-4mm

Dimensioni min componenti: 0201

Componente di dimensioni del chip standard: 0603 e superiori

Altezza massima componente □ 15mm

Passo minimo di piombo: 0,3 mm

Passo palla BGA min: 0.4mm

Precisione di posizionamento: +/- 0,03 mm